



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

5    Applicant:     Kuo-Ming Chen  
     Examiner:     Nguyen, Dilinh P  
     Filing Date: 05/21/2002     Art Unit:    2814  
     App. No.:      10/063,880     Docket No.: NAUP0481USA

10   Title:        SOLDER PADS FOR IMPROVING RELIABILITY OF A  
                     PACKAGE

     To:            Commissioner for Patents  
                     P.O. Box 1450  
15                   Alexandria VA 22313-1450

     Subject: Response to the Office action dated 06/04/2003

     Dear Sir or Madame:

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**INTRODUCTORY COMMENTS**

     In response to the Office action identified above,  
25   the above-identified application is to be amended as  
     indicated in the following sections. Consideration of  
     all amendments is politely requested.

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